

CYPRESS SEMICONDUCTOR CORPORATION

PRODUCT RELIABILITY REPORT

QUARTER 1, 1998



PERFORM PER THE REQUIREMENT OF 25-00008, RELIABILITY MONITOR PROGRAM SPECIFICATION

Marc Hartranft
Reliability Manager

STANDARD STRESS TEST DESCRIPTIONS

<u>TEST</u>	<u>DESCRIPTION</u>
HTOL	High Temp Op Life, 150°C, 5.75V
HTOL2	High Temp Op Life, 125°C, 5.75V
HTSSL	High Temp Steady State Life, 150°C, 5.75V
HTSSL2	High Temp Steady State Life, 125°C, 5.75V
DRET	Data Retention Test, Data Bake 165°C, Plastic
DRET2	Data Retention Test, Data Bake 250°C, Hermetic
PCT	Pressure Cooker Test, 121°C, 100%RH, No Bias
HAST	Hi-Accel Saturation Test, 140°C, 85%RH, 5.5V Bias
TC	Temp Cycle, 125°C to -40°C
TC2	Temp Cycle, 150°C to -65°C
HTS	High Temp Storage, 165°C, No Bias
TEV	Temperature Extreme Verification

WAFER FAB AREAS

<u>FAB #</u>	<u>LOCATION</u>
CA	San Jose, California
TX	Round Rock, Texas
MN	Bloomington, Minnesota
FR	MHS, France

ASSEMBLY LOCATION

<u>ID</u>	<u>COMPANY/LOCATION</u>
KOREA-A	Anam-Buchon/Korea
ASAT-B	Asat/Hongkong
USA-C	Cypress/USA
PHIL-D	Dynesem/Philippines
USA-E	Cypress-Minnesota/USA
INDNS-F	Astra/Indonesia
TAIWAN-G	ASE/Taiwan
KOREA-H	Hyundai/Korea
MALAY-J	ASE/Malaysia
THLAND-K	TMS/Thailand
KOREA-L	Anam-Seoul/Korea
PHIL-M	Anam/Philippines
USA-N	Express/USA
INDNS-O	Omedata/Indonesia
USA-P	Pantronix/USA
KOREA-Q	Anam-Bupyong/Korea
PHIL-R	Cypress/Philippines
USA-S	ATM/USA
TAIWAN-T	OSE/Taiwan
MALAY-U	Unisem/Malaysia
USA-V	Aplus/USA
USA-W	Toshiba/USA
ALPHA-X	Cypress Bangkok/Thailand
ALPHA-Y	Alphatech/Thailand
THLAND-Z	Hana/Thailand

DESCRIPTION OF DATA TABLE COLUMN HEADINGS

<u>COLUMN HEADING</u>	<u>DESCRIPTION OF COLUMN CONTENTS</u>
Division	Cypress Manufacturing Division
Test	Common code for the stress performed. See table on previous page for detail.
Test Condition	Tem/humidity/bias condition for the stress. See table on previous for detail
Device ID	Cypress part number
Date Code	Week in which specific lot was marked/sealed/molded.
Lot Number	Manufacturing (assembly) lot number
Function	Generic product family at Cypress
Description	Brief description of device function
Technology	Fabrication process technology.
Process	Generic fabrication process
Pkg Material	Generic packaging material
Pkg Type	Common code for standard package configuration (PDIP=Plastic Dual-In-Line-Package).
Pkg Location	Country Location + Initial of assembly house (see table on previous page for detail).
# Pins	Pin cont of package in which device is assembled.
Duration	Data Readpoint of stress. For Temp Cycle (TC) = Cycles; all other stresses=Hours.
# Test	Quantity of devices submitted to this stress/test.
# Failed	Quantity of devices failing at this specific readpoint.
Fail Mode	Failure analysis results from this test, if any.

**RELIABILITY DATA SUMMARY
(Q198)**

LONG TERM FAILURE RATE SUMMARY					
PROCESS	DEVICE HOURS			FAILED	FAILURE MODE
	150C	125C	TOTAL ¹ @ 150C		
FAMOS TOTAL	8,832	0	8,832	0	
FLASH TOTAL	68,332	0	68,332	0	
SRAM/LOGIC TOTAL	2,467,116	1,902,000	3,087,168	5	2 NON VISUAL, 1 OTHER, 1 TOPSIDE CRACKS, 1 LIFTING BOND
BICMOS TOTAL	0	0	NO DATA	NODATA	
LFR TOTAL	2,544,280	1,902,000	3,164,332	5	---
EARLY FAILURE RATE SUMMARY					
PROCESS	UNITS TESTED			FAILED	FAILURE MODE
	150C	125C	TOTAL		
FAMOS TOTAL	0	0	NO DATA	NO DATA	
FLASH TOTAL	528	0	528	0	
SRAM/LOGIC TOTAL	26,504	1,858	28,362	9	2 NON VISUAL, 3 OTHERS, 1 TOPSIDE SCRATCHES, 1 BROKEN BOND, 1 CHIP-OUTS, 1 TOPSIDE CRACKS
BICMOS TOTAL	0	1,474	1,474	0	
EFR TOTAL	27,032	3,332	30,364	9	---
HTSSL FAILURE RATE SUMMARY					
PROCESS	DEVICE HOURS			FAILED	FAILURE MODE
	150C	125C	TOTAL ¹ @ 150C		
FAMOS TOTAL	0	239,000	77,914	0	
FLASH TOTAL	0	28,560	9,311	0	
SRAM/LOGIC TOTAL	199,256	2,320,576	955,764	1	1 PARTICLE
BICMOS TOTAL	0	232,000	75,632	0	
HTSSL TOTAL	199,256	2,820,136	1,118,620	1	---
TEMP CYCLE FAILURE RATE SUMMARY					
PROCESS	DEVICE CYCLE			FAILED	FAILURE MODE
	150C	125C	TOTAL ¹ @ 150C		
FAMOS TOTAL	110,100	0	110,100	0	
FLASH TOTAL	50,000	0	50,000	0	
SRAM/LOGIC TOTAL	1,382,800	310,500	1,463,530	2	2 UNKOWN
BICMOS TOTAL	44,300	0	44,300	1	1 SPEED DEGRATION
TC TOTAL	1,587,200	310,500	1,667,930	3	---

¹ Equivalent Total Device Hours/cycle. Derating factors are used for lower stress condition.

**RELIABILITY DATA SUMMARY
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HAST FAILURE RATE SUMMARY					
PROCESS	DEVICE HOURS			FAILED	FAILURE MODE
	140C	130C	TOTAL ¹ @ 140C		
FAMOS TOTAL	0	0	NO DATA	NO DATA	
FLASH TOTAL	6,400	0	6,400	0	
SRAM/LOGIC TOTAL	12,619,640	0	12,619,640	22	4 LIFTED BOND, 2 SPEED DEGRATION, 2 UNKNOWN, 1 OTHER, 13 POPCORN
BICMOS TOTAL	0	0	NO DATA	NO DATA	
HAST TOTAL	12,626,040	0	12,626,040	22	---
LTOL FAILURE RATE SUMMARY					
PROCESS	DEVICE HOURS		FAILED	FAILURE MODE	
FAMOS TOTAL	NO DATA		NO DATA		
FLASH TOTAL	NO DATA		NO DATA		
SRAM/LOGIC TOTAL	62,000		0		
BICMOS TOTAL	NO DATA		NO DATA		
LTOL TOTAL	62,000		0	---	
PCT FAILURE RATE SUMMARY					
PROCESS	DEVICE HOURS		FAILED	FAILURE MODE	
FAMOS TOTAL	NO DATA		NO DATA		
FLASH TOTAL	NO DATA		NO DATA		
SRAM/LOGIC TOTAL	146,028		9	2 UNKNOWN, 7 TOPSIDE CRACKS	
BICMOS TOTAL	38,976		3	3 UNKNOWN	
PCT TOTAL	185,004		12	---	
DRET FAILURE RATE SUMMARY					
PROCESS	PLASTIC (165C)		HERMETIC(250C)		FAILURE MODE
	DHR	REJ	DHR	REJ	
FAMOS TOTAL	78,000	0	77,000	0	
FLASH TOTAL	124,920	0	NO DATA	NO DATA	
SRAM/LOGIC TOTAL	360,168	0	NO DATA	NO DATA	
BICMOS	141,872	0	NO DATA	NO DATA	
DRET TOTAL	704,960	0	77,000	0	---

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Technology	Test	Test Condition	Division	Function	Device	Eval#	D/C	Assembly Lot No	Description	Process	Wfr Loc	Pkg type	Assy Loc	No Pin	Dura tion	Qty Test	Qty Fail	Fail Mode		
BICMOS-SM1	DRET	165C/NO BIAS	DCD	CHNL	CY7B991-JC	M80154	9746	219711890	PSCB	BiCMOS	TX	PLCC	ALPHA-X	32	168	116	0			
				ENET	CY7B8392-JC	M74075	9716	519704354	TRANSCEIVER	BiCMOS	TX	PLCC	INDNS-O	28	168	76	0			
						M74088	9708	519701901	TRANSCEIVER	BiCMOS	TX	PLCC	INDNS-O	28	168	78	0			
	HTOL2	125C/6.5V	DCD	ENET	CY7B4663-JC	97482	9746	519712273	TRANSCEIVER	BiCMOS	TX	PLCC	INDNS-O	28	48	375	0			
							519712421	TRANSCEIVER	BiCMOS	TX	PLCC	INDNS-O	28	48	379	0				
							9806	219800826	TRANSCEIVER	BiCMOS	TX	PLCC	ALPHA-X	28	48	360	0			
							9809	219801540	TRANSCEIVER	BiCMOS	TX	PLCC	ALPHA-X	28	48	360	0			
	HTSSL2	125C/5.50V	DCD	CHNL	CY7B991-JC	M74067	9733	219708729	PSCB	BiCMOS	TX	PLCC	ALPHA-X	32	96	116	0			
	PCT	121C/100%RH	DCD	CHNL	CY7B991-JC	M74069	9733	219708729	PSCB	BiCMOS	TX	PLCC	ALPHA-X	32	96	77	0			
						M80155	9746	219711890	PSCB	BiCMOS	TX	PLCC	ALPHA-X	32	96	77	0			
					ENET	CY7B8392-JC	M74089	9708	519701901	TRANSCEIVER	BiCMOS	TX	PLCC	INDNS-O	28	96	78	0		
	TC2	-65C TO 150C	DCD	CHNL	CY7B991-JC	M80157	9746	219711890	PSCB	BiCMOS	TX	PLCC	ALPHA-X	32	300	45	1	1 SPEED DEGRADATION		

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BICMOS-SM1	TC2	-65C TO 150C	DCD	CHNL	CY7B991-JC	M80157	9746 219711890	PSCB	BiCMOS	TX	PLCC	ALPHA-X	32	1000	44	0	
	TEV	0 READ POINT	DCD	ENET	CY7B8392-JC	M74072	9716 519704354	TRANSCEIVER	BiCMOS	TX	PLCC	INDNS-O	28	-5 25 85	94 118 94	0 24 0	OTHERS
						M74086	9708 519701901	TRANSCEIVER	BiCMOS	TX	PLCC	INDNS-O	28	-5 25 85	105 116 105	0 11 0	OTHERS

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FAMOS-P20	HTSSL2	125C/5.75V	PLD	MAX	CY7C341-25JI	M73073	9724	619703645	REPROG.PAL	CMOS	TX	PLCC	KOREA-A	84	96	41	0	
															96	79	0	
															500	41	0	
															500	79	0	
															1000	41	0	
															1000	79	0	
															2000	40	0	
															2000	79	0	
	TC2	-65C TO 150C	PLD	MAX	CY7C341-JI	M72056	9711	619700872	REPROG.PAL	CMOS	TX	PLCC	KOREA-A	84	300	50	0	

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FAMOS-P26	DRET	165C/NO BIAS	MPD	PROM	CY27C010-PC	M80170	9738 619707247	128K x 8	CMOS	TX	PDIP	KOREA-H	32	168 1000	78 78	0 0	
	DRET2	250C/NO BIAS	MPD	PROM	CY27H010-WC	M73065	9726 219706752	128K x 8	CMOS	TX	WCER	ALPHA-X	32	168 1000	77 77	0 1 0	EOS
	HTOL	150C/5.75V	CPD	USB	CY7C63413-WSC	97394	9738 219709761	USB	CMOS	TX	WSBR	ALPHA-X	48	184	48	0	
	TC2	-65C TO 150C	CPD	USB	CY7C63413-WSC	97394	9738 219709761	USB	CMOS	TX	WSBR	ALPHA-X	48	100 1000	48 47	0 0	
			MPD	PROM	CY27C010-PC	M80171	9738 619707247	128K x 8	CMOS	TX	PDIP	KOREA-H	32	300 500 1000	48 48 48	0 0 0	
	TEV	0 READ POINT	MPD	PROM	CY27C010-PC	M80167	9738 619707247	128K x 8	CMOS	TX	PDIP	KOREA-H	32	-5 25 85	118 118 118	0 0 0	

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FLASH-FL28	DRET	165C/NO BIAS	PLD	FLASH	CY7C371I-JC	98116	9744	219711475	32-MCEL FL	CMOS	TX	PLCC	ALPHA-X	44	168 552	85 85	0 0	
	HAST	140C/5.5V	PLD	FLASH	CY7C371I-JC	98116	9744	219711475	32-MCEL FL	CMOS	TX	PLCC	ALPHA-X	44	128	50	0	
	HTOL	150C/5.75V	PLD	FLASH	CY7C371I-JC	98116	9744	219711475	32-MCEL FL	CMOS	TX	PLCC	ALPHA-X	44	48 80 500	528 119 119	0 0 0	
	HTSSL2	125C/5.75V	PLD	FLASH	CY7C371I-JC	98116	9744	219711475	32-MCEL FL	CMOS	TX	PLCC	ALPHA-X	44	80 168 336	85 85 85	0 0 0	
	TC2	-65C TO 150C	PLD	FLASH	CY7C371I-JC	98116	9744	219711475	32-MCEL FL	CMOS	TX	PLCC	ALPHA-X	44	300 1000	50 50	0 0	

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FLASH-FL28D	DRET	165C/NO BIAS	PLD	FLASH	CY7C374I-JC	M74052	9722	349611012	128 MCEL FL	CMOS	TX	PLCC	KOREA-A	84	168 1000	78 78	0 0	
	HTOL	150C/5.75V	PLD	FLASH	CY7C374I-YMB	97451	9737	219709957	128 MCEL FL	CMOS	TX	CLCC	ALPHA-X	84	184	48	0	
	TEV	0 READ POINT	PLD	FLASH	CY7C374I-JC	M74050	9722	349611012	128 MCEL FL	CMOS	TX	PLCC	KOREA-A	84	-5 25 85	116 116 116	0 0 0	
						M80172	9728	219707333	128 MCEL FL	CMOS	TX	PLCC	ALPHA-X	84	-5 25 85	116 116 116	0 0 0	

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SRAM/LOGIC-C2AN	DRET	165C/NO BIAS	CPD	VME	VIC068A-BC	M80165	9746 349705554	VME INTERF.	CMOS	MN	PPGA	PHIL-M	144	168 1000	77 77	0 0	

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SRAM/LOGIC-L20	DRET	165C/NO BIAS	CPD	VME	CY7C611A-NC	M74064	9728	349703682	RISC CONTRL	CMOS	TX	PQFP	HK-B	160	168	76	0	
														1000	76	0		
						M80183	9731	349704147	RISC CONTRL	CMOS	TX	PQFP	HK-B	160	168	78	0	
														1000	78	0		
	TC	-40C TO 125C	CPD	VME	CY7C611A-NC	M74062	9728	349703682	RISC CONTRL	CMOS	TX	PQFP	HK-B	160	500	46	0	
														1500	40	0 16	EXTERNAL CONTAMINATION	

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SRAM/LOGIC-L28	DRET	165C/NO BIAS	CPD	TTECH	CY2273APVC	97403	9740 619708289/	CLOCK SYN.	CMOS	TX	SSOP	CSPI-R	48	168	78	0	
														552	78	0	
							9745 619709731	CLOCK SYN.	CMOS	TX	SSOP	CSPI-R	48	168	78	0	
														552	78	0	
							619709732	CLOCK SYN.	CMOS	TX	SSOP	CSPI-R	48	168	78	0	
														552	78	0	
	HAST	140C/3.63V	CPD	TTECH	CY2273APVC	97403	9740 619708289/	CLOCK SYN.	CMOS	TX	SSOP	CSPI-R	48	128	44	0	
														256	44	0	
							9745 619709732	CLOCK SYN.	CMOS	TX	SSOP	CSPI-R	48	128	45	0	
	HTOL	150C/3.65V	CPD	TTECH	CY2273APVC	97403	9740 619708289/	CLOCK SYN.	CMOS	TX	SSOP	CSPI-R	48	48	30	0	
														48	150	0	
														48	150	0	
														80	116	0	
														500	116	0	
							9745 619709731	CLOCK SYN.	CMOS	TX	SSOP	CSPI-R	48	48	100	0	
														48	120	0	
														48	120	0	
														80	120	0	
														500	116	0	
							619709732	CLOCK SYN.	CMOS	TX	SSOP	CSPI-R	48	48	116	0	
														48	214	0	
														80	116	0	
														500	115	0	1 EOS
	HTS	165C/NO BIAS	CPD	TTECH	CY2273APVC	97403	9740 619708289/	CLOCK SYN.	CMOS	TX	SSOP	CSPI-R	48	336	45	0	
														500	45	0	
														1000	45	0	

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SRAM/LOGIC-L28	LTOL	-30C/6.5V	CPD	TTECH	CY2273APVC	97403	9740	619708289/	CLOCK SYN.	CMOS	TX	SSOP	CSPI-R	48	500 1000	45 45	0 0	1 EOS
	TC2	-65C TO 150C	CPD	TTECH	CY2273APVC	97403	9740	619708289/	CLOCK SYN.	CMOS	TX	SSOP	CSPI-R	48	300 1000	45 45	0 0	
							9745	619709731	CLOCK SYN.	CMOS	TX	SSOP	CSPI-R	48	300 1000	48 48	0 0	
							619709732	CLOCK SYN.	CMOS	TX	SSOP	CSPI-R	48	300 1000	47 47	0 0		

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SRAM/LOGIC-R21	HAST	140C/5.5V	MPD	COMDTY	CY7C185-VC	M80147	9745	619709631	SML/64K	CMOS	TX	SOJ	CSPI-R	28	128	76	0	
	HTOL2	125C/5.75V	MPD	COMDTY	CY7C185-VI	M74027	9734	519708252	SML/64K	CMOS	TX	SOJ	INDNS-O	28	96	115	0	
															500	115	0	
															1000	115	0	
															2000	115	0	
					CY7C186-ZC	M74010	9725	619704309	SML/64K	CMOS	TX	TSOP	KOREA-Q	32	96	116	0	
															500	116	0	
															1000	116	0	
															2000	116	0	
	HTSSL2	125C/5.50V	MPD	COMDTY	CY7C185-45PC	M73029	9723	219705968	SML/64K	CMOS	TX	PDIP	ALPHA-X	28	96	120	0	4 EOS
															500	116	0	
															1000	116	0	
															2000	116	0	
					CY7C185-VI	M74028	9734	519708252	SML/64K	CMOS	TX	SOJ	INDNS-O	28	96	115	0	
															500	115	0	
															1000	115	0	
															2000	115	0	
	TEV	0 READ POINT	MPD	COMDTY	CY7C185-VC	M80144	9745	619709631	SML/64K	CMOS	TX	SOJ	CSPI-R	28	-5	116	0	
															25	116	0	
															85	116	0	

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SRAM/LOGIC-R28	HAST	140C/3.63	DCD	SPCM	CY7C4245-JC	97272	9749	349705972	4Kx18 FIFO	CMOS	MN	PLCC	PHIL-M	32	128	48	0			
		140C/5.5V	DCD	SPCM	CY7C136-JC	M80124	9742	519713305	2K x 8 DP	CMOS	MN	PLCC	INDNS-O	52	128	77	1 1	LIFTING BOND/S		
					CY7C4245-AC	M74060	9729	619705320	4Kx18 FIFO	CMOS	MN	TQFP	KOREA-Q	64	128	78	0			
					M80149	9728	619704566	4Kx18 FIFO	CMOS	MN	TQFP	KOREA-Q	64	128	76	0				
		MPD	COMDTY	CY7C1009-VC	M80129	9741	619708282	256K x 4	CMOS	MN	SOJ	CSPI-R	32	128	77	0				
				CY7C188-VC	M80137	9745	349705798	32K x 9	CMOS	MN	SOJ	PHIL-M	32	128	67	0				
				CY7C199-VC	M80115	9746	619709733	32K x 8	CMOS	TX	SOJ	CSPI-R	28	128	77	2 2	SPEED DEGRADATION			
				M80197	9808	619802072	32K x 8	CMOS	TX	SOJ	CSPI-R	28	128	76	0					
				M80198	9808	619801874	32K x 8	CMOS	TX	SOJ	CSPI-R	28	128	76	0					
		HTOL	150C/3.8V	DCD	SPCM	CY7C4245-JC	97272	9749	349705972	4Kx18 FIFO	CMOS	MN	PLCC	PHIL-M	32	48 80 500	1532 130 130	0 0 0		
			150C/5.75V	MPD	COMDTY	CY7C199-VC	98082	9803	619800042N	32K x 8	CMOS	TX	SOJ	CSPI-R	28	48	1373	0		
									619800397N	32K x 8	CMOS	TX	SOJ	CSPI-R	28	48	1445	0		
						9804	619800236N	32K x 8	CMOS	TX	SOJ	CSPI-R	28	48	1459	0				
	HTOL2	125C/5.75V	MPD	COMDTY	CY7C1009-VC	M74015	9732	619705971	256K x 4	CMOS	MN	SOJ	CSPI-R	32	96 500 1000 2000	116 114 114 114	1 1 0 1 0 0 2	TOPSIDE SCRATCHES ESD EOS		
					CY7C109-VC	M74021	9734	519708340	128K x 8	CMOS	MN	SOJ	INDNS-O	32	96	115	0			

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SRAM/LOGIC-R28	HTOL2	125C/5.75V	MPD	COMDTY	CY7C109-VC	M74021	9734	519708340	128K x 8	CMOS	MN	SOJ	INDNS-O	32	500	115	0	
															1000	115	0	
															2000	115	0	
					CY7C199-ZI	M74033	9730	619705361	32K x 8	CMOS	MN	TSOP	CSPI-R	28	96	116	0	
															500	115	0	
															1000	115	0	
															2000	115	0	
	HTSSL	150C/3.63V	DCD	SPCM	CY7C4245-JC	97272	9749	349705972	4Kx18 FIFO	CMOS	MN	PLCC	PHIL-M	32	80	78	0	
														168	78	0		
	HTSSL2	125C/5.50V	MPD	COMDTY	CY7C109-VC	M73035	9722	519705873	128K x 8	CMOS	MN	SOJ	TAIWN-G	32	96	120	0	
														500	120	0		
														1000	120	0		
														2000	120	0		
						M74022	9734	519708340	128K x 8	CMOS	MN	SOJ	INDNS-O	32	96	116	0	
															500	116	0	
															1500	116	0	
															2000	116	0	
		125C/5.5V	MPD	COMDTY	CY7C1009-VC	M74016	9732	619705971	256K x 4	CMOS	MN	SOJ	CSPI-R	32	96	116	0	1 EOS
															500	115	0	
															1000	115	1	1 PARTICLE
															2000	113	0	1 EOS
					CY7C199-ZI	M74034	9730	619705361	32K x 8	CMOS	MN	TSOP	CSPI-R	28	96	116	0	
															500	116	0	
															1000	116	0	
															2000	116	0	
	PCT	121C/100%RH	DCD	SPCM	CY7C136-JC	M80123	9742	519713305	2K x 8 DP	CMOS	MN	PLCC	INDNS-O	52	96	77	0	
															168	77	0	

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SRAM/LOGIC-R28	PCT	121C/100%RH	DCD	SPCM	CY7C4245-AC	M80148	9728	619704566	4Kx18 FIFO	CMOS	MN	TQFP	KOREA-Q	64	96 168	77 77	0 0						
				MPD	COMDTY	CY7C199-ZI	M74035	9730	619705361	32K x 8	CMOS	MN	TSOP	CSPI-R	28	96 168	77 58	0 3	EOS				
	TC2	-65C TO 150C	DCD	SPCM	CY7C136-JC	M74001	9716	349616269	2K x 8 DP	CMOS	MN	PLCC	PHIL-M	52	300 500 1000	46 46 46	0 0 2	UNKNOWN					
						M80125	9742	519713305	2K x 8 DP	CMOS	MN	PLCC	INDNS-O	52	300 500 1000	46 46 46	0 0 0						
						CY7C4221-AC	97272	9801	619711520	1Kx9 FIFO	CMOS	MN	TQFP	KOREA-A	32	300	55		0				
						CY7C4221-JC	97272	9751	219713130	1Kx9 FIFO	CMOS	MN	PLCC	ALPHA-X	32	300 1000	48 48		0 0				
						CY7C4235-JC	97272	9805	619800785	2Kx18 FIFO	CMOS	MN	PLCC	KOREA-A	32	300	54		0				
						CY7C4245-AC	M80150	9728	619704566	4Kx18 FIFO	CMOS	MN	TQFP	KOREA-Q	64	300 500 1000	48 48 48		0 0 0				
						MPD	COMDTY	CY7C109-VC	M80186	9749	519713657	128K x 8	CMOS	MN	SOJ	INDNS-O	32		300 500 1000	45 45 45	0 0 0		
					TEV	0 READ POINT	DCD	SPCM	CY7C136-JC	M80120	9742	519713305	2K x 8 DP	CMOS	MN	PLCC	INDNS-O		52	-5 25 85	116 116 116	0 0 0	
									MPD	COMDTY	CY7C1009-VC	M80126	9741	619708282	256K x 4	CMOS	MN		SOJ	CSPI-R	32	-5	117

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SRAM/LOGIC-R28	TEV	0 READ POINT	MPD	COMDTY	CY7C1009-VC	M80126	9741 619708282	256K x 4	CMOS	MN	SOJ	CSPI-R	32	25	117	0	
														85	117	0	
					CY7C188-VC	M80134	9745 349705798	32K x 9	CMOS	MN	SOJ	PHIL-M	32	-5	116	0	
														25	116	0	
														85	116	0	
					CY7C199-VC	M80179	9748 619710553	32K x 8	CMOS	MN	SOJ	PHIL-GW	28	-5	117	0	
														25	117	0	
														85	117	0	

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SRAM/LOGIC-R3	HAST	140C/3.63V	MPD	COMDTY	CY7C1021-BSC	97354	9739	349705285	64K x16	CMOS	MN	MBGA	TAIWN-G	48	36 128	52 52	0 0																	
								349705286	64K x16	CMOS	MN	MBGA	TAIWN-G	48	36 128	52 51	0 0																	
		140C/5.5V	MPD	COMDTY	CY7C1021-ZSC	97491	9746	619708845L	64K x16	CMOS	MN	TSOP	TAIWN-T	44	128	54	0																	
				SYNC	CY7C1031-JC	98093	9740	519710279	64K x 18	CMOS	MN	PLCC	INDNS-O	52	128 256	46 44	2 2	LIFTED BOND																
																			519710280	64K x 18	CMOS	MN	PLCC	INDNS-O	52	128	46	1	1	LIFTED BOND				
																			M74099	9737	519709659	64K x 18	CMOS	MN	PLCC	INDNS-O	52	128 128	22 54	0 1	EOS/1	OTHERS		
																			M80161	9742	519710953	64K x 18	CMOS	MN	PLCC	INDNS-O	52	128 128	27 50	0 0	EOS EOS			

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SRAM/LOGIC-R3	HTS	165C/NO BIAS	MPD	COMDTY	CY7C1021-BSC	97354	9739	349705284	64K x16	CMOS	MN	MBGA	TAIWN-G	48	336	50	0	
															500	50	0	
															1000	50	0	
					CY7C1021-ZSC	97491	9746	619708845L	64K x16	CMOS	MN	TSOP	TAIWN-T	44	336	50	0	
	HTSSL	150C/5.75V	MPD	SYNC	CY7C1031-JC	98093	9727	519706959	64K x 18	CMOS	MN	PLCC	INDNS-O	52	80	76	0	
																168	76	0
							9731	519708075	64K x 18	CMOS	MN	PLCC	INDNS-O	52	80	77	0	
																168	77	0
	HTSSL2	125C/5.50V	MPD	SYNC	CY7C1031-JC	M74097	9737	519709659	64K x 18	CMOS	MN	PLCC	INDNS-O	52	96	116	0	4 EOS
															500	116	0	
															1000	116	0	
															2000	116	0	
		125C/5.5V	MPD	COMDTY	CY7C199-VC	M74046	9729	619705121	256K	CMOS	MN	SOJ	CSPI-R	28	96	116	0	
															500	116	0	
															1000	116	0	
															2000	116	0	
	PCT	121C/100%RH	MPD	COMDTY	CY62256V-ZC	M73081	9650	349613775	32K x 8	CMOS	CA	TSOP	PHIL-M	28	96	79	7	TOPSIDE CRACKS
															168	69	0	2 EOS
						M74092	9705	349700731	32K x 8	CMOS	CA	TSOP	PHIL-M	28	96	76	0	
															168	76	1	1 UNKNOWN
					CY7C199-VC	M80189	9802	619711953	256K	CMOS	MN	SOJ	CSPI-R	28	54	81	0	
															96	81	0	
															168	81	0	

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SRAM/LOGIC-R3	PCT	121C/100%RH	MPD	COMDTY	CY7C199-VC	M80190			256K	CMOS	MN	SOJ	CSPI-R	28	54	75	0														
																96	75		0												
																168	75		0												
						M80191	9750	619710984	256K	CMOS	MN	SOJ	CSPI-R	28	54	99	0														
															96	99	0														
															168	99	1 1 TOPSIDE CRACKS														
					SYNC	CY7C1031-JC	M74098	9737	519709659	64K x 18	CMOS	MN	PLCC	INDNS-O	52	96	77	0													
																	M80162	9742		519710953	64K x 18	CMOS	MN	PLCC	INDNS-O	52	96	77	0 3 EXTERNAL CONTAMINATION		
							168	74	0																						
	T/S	-55C TO 150C	MPD	COMDTY	CY7C1021-BSC	97354	9739	349705284	64K x16	CMOS	MN	MBGA	TAIWN-G	48	100	50	0														
																200	50		0												
					CY7C1021-ZSC	97491	9746	619708845L	64K x16	CMOS	MN	TSOP	TAIWN-T	44	100	50	0														
																200	50		0												
	TC	-40C TO 125C	MPD	COMDTY	CY7C1021-BSC	97354	9739	349705284	64K x16	CMOS	MN	MBGA	TAIWN-G	48	500	55	0														
															1000	55	0														
															1500	55	0														
									349705285	64K x16	CMOS	MN	MBGA	TAIWN-G	48	500	55	0													
																1000	55	0													
																1500	55	0													
						349705286	64K x16	CMOS	MN	MBGA	TAIWN-G	48	500	55	0																
													1000	55	0																
													1500	55	0																
													TC2	-65C TO 150C	MPD	COMDTY	CY7C1021-ZSC	97491	9746	619708843L	64K x16	CMOS	MN	TSOP	TAIWN-T	44	300	50	0		
																											1000	50	0		
619708844L	64K x16	CMOS	MN	TSOP	TAIWN-T	44	300	50	0																						

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SRAM/LOGIC-R3	TC2	-65C TO 150C	MPD	COMDTY	CY7C1021-ZSC	97491	9746	619708844L	64K x16	CMOS	MN	TSOP	TAIWN-T	44	1000	50	0																	
								619708845L	64K x16	CMOS	MN	TSOP	TAIWN-T	44	300 1000	50 50	0 0																	
					SYNC	CY7C1031-JC	98093	9731	519708075	64K x 18	CMOS	MN	PLCC	INDNS-O	52	300	86	0																
								9740	519710280	64K x 18	CMOS	MN	PLCC	INDNS-O	52	300	46	0																
									519710281	64K x 18	CMOS	MN	PLCC	INDNS-O	52	300	46	0																
								M74100	9737	519709659	64K x 18	CMOS	MN	PLCC	INDNS-O	52	300	46	0															
																	500	46	0															
																	1000	46	0															
							1500										46	0																
								2000	46	0																								
								3000	46	0																								
							M80163	9742	519710953	64K x 18	CMOS	MN	PLCC	INDNS-O	52	300	46	0																
																500	46	0																
																1000	46	0																
			TEV	0 READ POINT	MPD	COMDTY	CY7C199-VC	M80192	9802	619711953	256K	CMOS	MN	SOJ	CSPI-R	28	-5	117	1 1	UNKNOWN														
																	25	117	0															
																	85	115	0															
			SYNC	CY7C1031-JC	M80158	9742	519710953	64K x 18	CMOS	MN	PLCC	INDNS-O	52	-5	116	0																		
																		25	116	0														
																		85	116	0														

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SRAM/LOGIC-R31	HAST	140C/3.0V	MPD	SYNC	CY7C1399-ZC	M73001	9645 349613772	32K x 8	CMOS	CA	TSOP	PHIL-M	28	128	8	1 1	UNKNOWN
														128	72	0	
		140C/3.3V	MPD	SYNC	CY7C1399-VC	M80111	9744 619709194	32K x 8	CMOS	MN	SOJ	PHIL-M	28	128	21	0	
														128	56	0	
	HTOL2	125C/3.80V	MPD	SYNC	CY7C1399-VC	M74039	9727 619704667	32K x 8	CMOS	MN	SOJ	PHIL-M	28	96	116	0	
														500	116	0	
														1000	116	0	
														2000	116	0	
	HTSSL2	125C/3.63V	MPD	SYNC	CY7C1399-VC	M74040	9727 619704667	32K x 8	CMOS	MN	SOJ	PHIL-M	28	96	116	0	
														500	116	0	
														1000	116	0	
														2000	116	0 2	EOS

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SRAM/LOGIC-R32	HAST	140C/3.3V	MPD	SYNC	CY6157R202V0-ZA	97294	9744	349705604L	256K/2M ROM	CMOS	MN	STSO	TAIWAN-T	32	128	48	0	
		140C/5.5V	MPD	COMDTY	CY62256-SNC	M73012	9720	519705368	32K x 8	CMOS	CA	NSOI	INDNS-O	28	128	77	0 1	EOS
						M80119	9744	519710283	32K x 8	CMOS	CA	NSOI	INDNS-O	28	128	76	0	
					CY7C109-VC	M80133	9745	519712223	128K x 8(5)	CMOS	MN	SOJ	INDNS-O	32	128	75	14 13	POPCORN/1 UNKNOWN
	HTOL	150C/3.45V	MPD	SYNC	CY6157R202V0-ZA	97294	9744	349705604L	256K/2M ROM	CMOS	MN	STSO	TAIWAN-T	32	48	759	0	
																80	117	0
																500	117	0 1 MIXED AT BIN
	150C/3.80V	MPD	COMDTY	CY62128V-SC	97499	9751	719710244	128K x 8	CMOS	MN	SOIC	TAIWAN-G	32	48	1747	0		
	150C/4.45V	MPD	SYNC	CY6157R202V0-ZA	97294	9747	619710102L	256K/2M ROM	CMOS	MN	STSO	TAIWAN-T	32	48	757	0		
															80	118	0	
															500	118	0	
	150C/5.75V	MPD	COMDTY	CY62128-SC	97499	9743	619708508D	128K x 8	CMOS	MN	SOIC	TAIWAN-G	32	48	1267	0 1	EOS	
								619708595	128K x 8	CMOS	MN	SOIC	TAIWAN-G	32	48	1265	0	
								619708666	128K x 8	CMOS	MN	SOIC	TAIWAN-G	32	48	1278	0	
								9746 619709300	128K x 8	CMOS	MN	SOIC	TAIWAN-G	32	48	913	0	
				CY62256-SNC	97329	9735	519709032/	32K x 8	CMOS	MN	NSOI	INDNS-O	28	48	513	0		
															48	513	0	
48															513	0		
80															380	0		
500															379	0 1 EOS		
97468	9740	519710622D	32K x 8	CMOS	MN	NSOI	INDNS-O	28	48	1195	0 1	EOS						
										9803 519800538/	32K x 8	CMOS	MN	NSOI	INDNS-O	28	48	3522

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SRAM/LOGIC-R32	HTOL	150C/5.75V	MPD	COMDTY	CY62256-SNC	98076	9805	519801105/	32K x 8	CMOS	MN	NSOI	INDNS-O	28	48	3783	0	
					CY62256-SNI	97468	9741	519710876/	32K x 8	CMOS	MN	NSOI	INDNS-O	28	48	1140	1 1	NON VISUAL
								519710879/	32K x 8	CMOS	MN	NSOI	INDNS-O	28	48	1200	0	
	HTOL2	125C/5.75V	MPD	COMDTY	CY62256-SNC	M74005	9732	519707894	32K x 8	CMOS	CA	NSOI	INDNS-O	28	96	116	0	
															500	114	0 1	EOS
															1000	114	0	
															2000	114	0	
	HTSSL	150C/3.3V	MPD	SYNC	CY6157R202V0-ZA	97294	9744	349705604L	256K/2M ROM	CMOS	MN	STSO	TAIWAN-T	32	80	78	0	
															168	78	0	
							9747	619710102L	256K/2M ROM	CMOS	MN	STSO	TAIWAN-T	32	80	78	0	
															168	78	0	
	HTSSL2	125C/5.50V	MPD	COMDTY	CY62256-SNC	M74006	9732	519707894	32K x 8	CMOS	CA	NSOI	INDNS-O	28	96	116	0 1	EOS
															500	115	0	
															1000	115	0	
															2000	115	0	
	PCT	121C/100%RH	MPD	COMDTY	CY62256-SNC	M80188	9744	519710283	32K x 8	CMOS	CA	NSOI	INDNS-O	28	96	76	0	
															168	76	0	
	TC2	-65C TO 150C	MPD	COMDTY	CY62256-SNC	M80187	9744	519710283	32K x 8	CMOS	CA	NSOI	INDNS-O	28	300	45	0	
															500	45	0	
															1000	45	0	

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SRAM/LOGIC-R32	TC2	-65C TO 150C	MPD	SYNC	CY6157R202V0-ZA	97294	9744	349705604L	256K/2M ROM	CMOS	MN	STSO	TAIWAN-T	32	300	48	0		
															1000	48	0		
								9747	619710102L	256K/2M ROM	CMOS	MN	STSO	TAIWAN-T	32	300	48	0	
															1000	48	0		
	TEV	0 READ POINT	MPD	COMDTY	CY62256-SNC	M80116	9744	519710283	32K x 8	CMOS	CA	NSOI	INDNS-O	28	-5	117	0		
															25	117	0		
					CY62256V-ZC	M80138	9749	619710170	32K x 8	CMOS	MN	TSOP	CSPI-G	28	-5	116	0		
															25	116	0		
														85	116	0			

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SRAM/LOGIC-R32D	HAST	140C/5.5V	MPD	COMDTY	CY7C1049-VC	M80104	9747	619709647	512K x 8	CMOS	MN	SOJ	KOREA-L	36	128	78	0	
	PCT	121C/100%RH	MPD	COMDTY	CY7C1049-VC	M80106	9747	619709647	512K x 8	CMOS	MN	SOJ	KOREA-L	36	96	79	0	1 LASER FUSE INC. SERVER
	TC2	-65C TO 150C	MPD	COMDTY	CY7C1049-VC	M80105	9747	619709647	512K x 8	CMOS	MN	SOJ	KOREA-L	36	300 500	48 48	0 0	
	TEV	0 READ POINT	MPD	COMDTY	CY7C1049-VC	M80101	9747	619709647	512K x 8	CMOS	MN	SOJ	KOREA-L	36	-5 25 85	118 119 118	0 1 0	1 OTHERS

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Technology	Test	Test Condition	Division	Function	Device	Eval#	D/C	Assembly Lot No	Description	Process	Wfr Loc	Pkg type	Assy Loc	No Pin	Duration	Qty Test	Qty Fail	Fail Mode
SRAM/LOGIC-R33	HTOL	150C/4.3V	MPD	COMDTY	CY7C1021V33-BSC	97354	9738	619706882	64K x16	CMOS	MN	MBGA	TAIWN-G	48		48	86	0
																48	185	0
																48	355	0
																80	116	0
																401	116	0
	HTOL2	125C/4.30V	MPD	COMDTY	CY7C1021V33-BSC	97354	9740	619706884	64K x16	CMOS	MN	MBGA	TAIWN-G	48		48	150	0
																48	288	0

CYPRESS SEMICONDUCTOR CORPORATION
PRODUCT RELIABILITY REPORT

Cypress Semiconductor Corporation
Quarterly Reliability Report
Quarter 1, 1998

Technology	Test	Test Condition	Division	Function	Device	Eval#	D/C	Assembly Lot No	Description	Process	Wfr Loc	Pkg type	Assy Loc	No Pin	Dura tion	Qty Test	Qty Fail	Fail Mode
SRAM/LOGIC-R42	HAST	140C/3.63	MPD	COMDTY	CY62256V-VC	97496	9740	619708056	32K x 8	CMOS	MN	SOJ	CSPI-R	28	128 256	45 45	0 0	
		140C/3.63V	MPD	COMDTY	CY62256V-VC	97465	9745	619709356/	32K x 8	CMOS	MN	SOJ	CSPI-R	28	128 256	47 47	0 0	
						97496	9745	619709132/	32K x 8	CMOS	MN	SOJ	CSPI-R	28	128	45	0	
	HTOL	150C/3.90V	MPD	COMDTY	CY62256V-VC	97465	9745	619709356/	32K x 8	CMOS	MN	SOJ	CSPI-R	28	80 500 1000	118 116 115	0 0 0	
						97496	9710	619702695/	32K x 8	CMOS	MN	SOJ	CSPI-R	28	80 500 1000	533 533 533	0 0 0	
							9725	619703951/	32K x 8	CMOS	MN	SOJ	CSPI-R	28	80 500	530 530	0 0	
								619703998/	32K x 8	CMOS	MN	SOJ	CSPI-R	28	80 500	530 529	1 1 1 1	OTHERS TOPSIDE CRACKS
	HTS	165C/NO BIAS	MPD	COMDTY	CY62256V-VC	97496	9719	619702695/	32K x 8	CMOS	MN	SOJ	CSPI-R	28	336 1000	48 48	0 0	
	HTSSL	150C/3.90V	MPD	COMDTY	CY62256V-VC	97465	9745	619709356/	32K x 8	CMOS	MN	SOJ	CSPI-R	28	80 168	78 77	0 1 0	EOS
						97496	9710	619702695/	32K x 8	CMOS	MN	SOJ	CSPI-R	28	80 168	157 157	0 0	
							9725	619703951/	32K x 8	CMOS	MN	SOJ	CSPI-R	28	80 168 248	165 165 165	0 0 0	

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Technology	Test	Test Condition	Division	Function	Device	Eval#	Assembly D/C	Lot No	Description	Process	Wfr Loc	Pkg type	Assy Loc	No Pin	Dura tion	Qty Test	Qty Fail	Fail Mode
SRAM/LOGIC-R42	HTSSL	150C/3.90V	MPD	COMDTY	CY62256V-VC	97496	9725	619703998/	32K x 8	CMOS	MN	SOJ	CSPI-R	28	80 168	165 165	0 0	
	LTOL	-30C/4.3V	MPD	COMDTY	CY62256V-VC	97496	9719	619702695/	32K x 8	CMOS	MN	SOJ	CSPI-R	28	500	45	0	
	TC2	-65C TO 150C	MPD	COMDTY	CY62256V-VC	97465	9745	619709356/	32K x 8	CMOS	MN	SOJ	CSPI-R	28	300 1000	90 90	0 0	
						97496	9710	619702695/	32K x 8	CMOS	MN	SOJ	CSPI-R	28	300 1000	91 91	0 0	
							9725	619703951/	32K x 8	CMOS	MN	SOJ	CSPI-R	28	300 1000	90 90	0 0	
								619703998/	32K x 8	CMOS	MN	SOJ	CSPI-R	28	300 1000	90 90	0 0	

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PRODUCT RELIABILITY REPORT

Cypress Semiconductor Corporation
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Technology	Test	Test Condition	Divi- sion	Func- tion	Device	Eval#	Assembly D/C Lot No	Descr Description	Pro- cess	Wfr Loc	Pkg type	Assy Loc	No Pin	Dura tion	Qty Test	Qty Fail	Fail Mode
SRAM/LOGIC-R42D	HAST	140C/3.63	MPD	SYNC	CY7C1334-AC	97328	9752 349706242	64K x 32	CMOS	MN	TQFP	TAIWN-G	100	128 256	48 48	0 0	
	HTOL	150C/3.8V	MPD	SYNC	CY7C1334-AC	97328	9752 349706242	64K x 32	CMOS	MN	TQFP	TAIWN-G	100	80 500	530 530	0 1	1 LIFTING BOND/S
							9801 619711701	64K x 32	CMOS	MN	TQFP	TAIWN-G	100	80 500	525 515	0 0	
	HTSSL	150C/3.63V	MPD	SYNC	CY7C1334-AC	97328	9752 349706242	64K x 32	CMOS	MN	TQFP	TAIWN-G	100	80 168	78 78	0 0	
		150C/63V	MPD	SYNC	CY7C1334-AC	97328	9801 619711701	64K x 32	CMOS	MN	TQFP	TAIWN-G	100	80 168	78 78	0 0	
	TC2	-65C TO 150C	MPD	SYNC	CY7C1334-AC	97328	9752 349706242	64K x 32	CMOS	MN	TQFP	TAIWN-G	100	300 1000	49 49	0 0	
							9801 619711701	64K x 32	CMOS	MN	TQFP	TAIWN-G	100	300	49	0	